

# Datacon 2200 evo

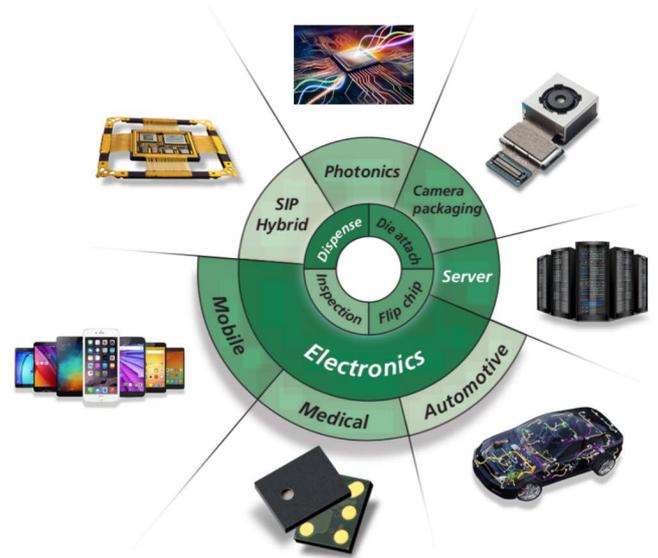


## Innovative Solution for Innovative Products

The Datacon 2200 evo die bonder for Multi Module Attach assembles all kinds of technologies on a tried-and-tested platform, enhanced with key features for high bonding accuracy and lower cost of ownership.

Besides unbeaten flexibility and full customization possibilities, this evolutionary machine offers high accuracy with long-term stability using a new camera system, higher speed through a new image processing unit, and improved cleanroom capabilities.

## Future Proof Equipment



### Datacon 2200 evo

#### Enhancements

- Accuracy
- Productivity
- Flexibility

#### Features

- Multi-Chip Capability
- Flexibility for Customizing
- Open Platform Architecture

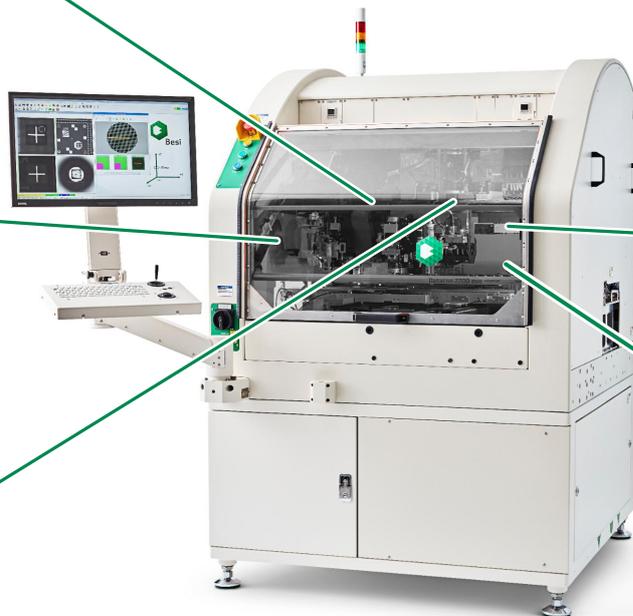
8 WEEKS  
LEAD TIME



TOOL-TO-TOOL  
REPEATABILITY



FLEXIBILITY



ACCURACY



MULTI-CHIP





### Multi-Chip

- Fully automatic cycle for Multi-Chip production
- Up to 7 Pick & Place tools (optionally 14), 5 eject tools
- Pressure/time (Musashi®), Auger, Jetter type dispensers available
- Epoxy stamping option
- Filled and unfilled epoxy, wide viscosity range



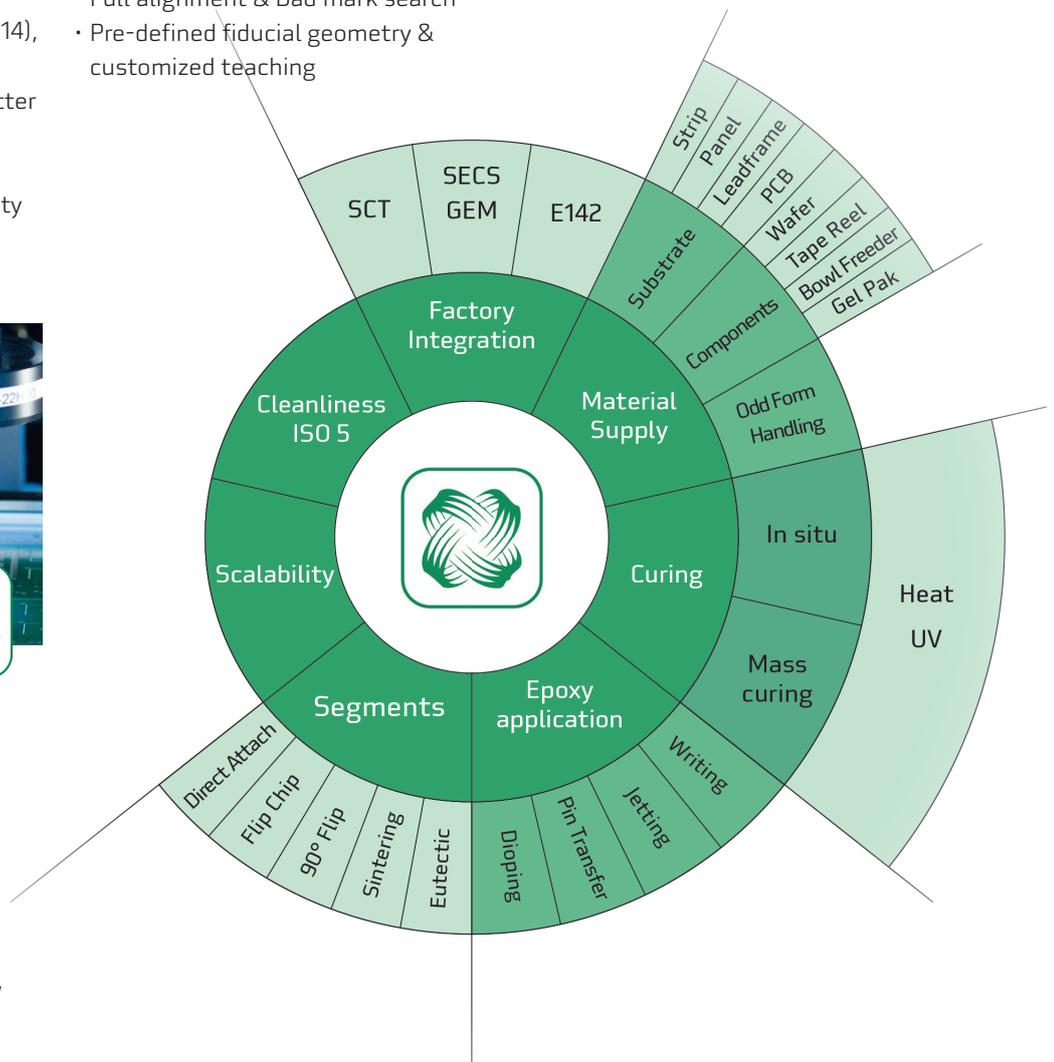
### Accuracy

- New high-speed image processing unit
- Full alignment & Bad mark search
- Pre-defined fiducial geometry & customized teaching



### Pick & Place Head

- Die Attach, Flip Chip and Multi-Chip in one machine
- Die pick from: wafer, waffle pack, Gel-Pak®, feeder
- Die place to: substrate, boat, carrier, PCB, leadframe, wafer
- Hot and cold processes supported: epoxy, soldering, thermo-compression, eutectic



### Performance

- X/Y placement accuracy:  $\pm 10 \mu\text{m}$  @ 3s
- Theta placement accuracy:  $\pm 0.15^\circ$  @ 3s

### Bond Heads

- Standard bond head  $0^\circ - 360^\circ$  rotation
- Heated bond head (optional)

### Footprint

- L x D x H: 1160 mm x 1225 mm x 1750 mm
- Statistics
- Uptime > 98 %
- Yield > 99.95 %

### Wafer

- Die size Die attach: 0.17 mm - 50 mm
- Die thickness: 0.17 mm - 7 mm
- Wafer size: 2" - 12" (50 mm - 300 mm)

### Chip Trays

- Waffle pack / Gel-Pak® 2" x 2" and 4" x 4"
- JEDEC tray on request
- Substrates and Carriers

### Substrate working range

- 13" x 8" (325 mm x 200 mm)